

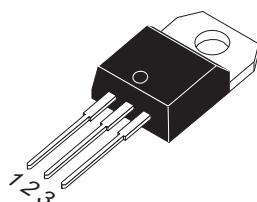


Description

Passivated high commutation triacs in a plastic envelope intended for use in circuits where high static and dynamic dV/dt and high di/dt can occur. These devices will commutate the full rated ms current at the maximum rated junction temperature without the aid of a snubber.

Simplified outline

TO-220AB



Features

- Blocking voltage to 600 V
- On-state RMS current to 16 A

Symbol



Applications

- Motor control
- Industrial and domestic lighting
- Heating
- Static switching

| Pin | Description |
|-----|----------------------|
| 1 | Main terminal 1 (T1) |
| 2 | Main terminal 2 (T2) |
| 3 | gate (G) |
| TAB | Main terminal 2 (T2) |

| SYMBOL | PARAMETER | Value | Unit |
|---------------------|--|-------|------|
| V_{DRM} | Repetitive peak off-state voltages | 600 | V |
| $I_T \text{ (RMS)}$ | RMS on-state current (full sine wave) | 16 | A |
| I_{TSM} | Non-repetitive peak on-state current (full cycle, $T_j \text{ initial}=25^\circ\text{C}$) | 168 | A |

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------|----------------------|------------|-----|-----|-----|---------------------------|
| $R_{th(j-c)}$ | Junction to case(AC) | | - | 1.2 | - | $^\circ\text{C}/\text{W}$ |
| $R_{th(j-a)}$ | Junction to ambient | | - | 60 | - | $^\circ\text{C}/\text{W}$ |



Limiting values in accordance with the Maximum system(IEC 134)

| SYMBOL | PARAMETER | CONDITIONS | | | MIN | Value | UNIT |
|-------------------|---|----------------------------------|-----------------|----------|-----|------------------------|------|
| V_{DSM}/V_{RSM} | Non repetitive surge peak off-state voltage | tp=10ms Tj=25°C | | | - | $V_{DRM}/V_{RRM} +100$ | V |
| $I_{T(RMS)}$ | RMS on-state current | Full sine wave; Tc=100°C | | | - | 16 | A |
| I_{TSM} | Non repetitive surge peak on-state current | full cycle, Tj initial= 25 °C | F=50Hz t=20ms | - | 160 | A | |
| | | | F=60Hz t=16.7ms | - | 168 | A | |
| I^2t | I^2t Value for fusing | tp=10ms | | | - | 144 | A²s |
| dI/dt | Critical rate of rise of on-state current | $I_g=2x I_{GT, tr \leq 100ns}$ | F=120Hz | Tj=125°C | - | 50 | A/μs |
| I_{GM} | Peak gate current | tp=20us | Tj=125°C | - | 4 | A | |
| I_{DRM} | $V_{DRM}=V_{RRM}$ | | Tj=25°C | - | 5 | μA | |
| I_{RRM} | $V_{DRM}=V_{RRM}$ | | Tj=125°C | - | 2 | mA | |
| $P_{G(AV)}$ | Average gate power dissipation | | Tj=125°C | - | 1 | W | |
| T_{stg} | Storage junction temperature range | | | -40 | 150 | °C | |
| T_j | Operating junction temperature range | | | -40 | 125 | °C | |

$T_j = 25^\circ\text{C}$ unless otherwise stated

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------|-----------|---|-------------|-----|-----|------------------------|
| Static characteristics | | | | | | |
| $I_{GT}(1)$ | | $V_d=12V; R_L=33\Omega$ | I-II-III | - | - | 10 mA |
| V_{GT} | | | I-II-III | | | 1.3 V |
| I_L | | $I_g=1.2 I_{GT}$ | I-III II | - | - | 25 mA 30 mA |
| $I_h(2)$ | | $I_t=500mA$ | - | - | 15 | mA |
| V_{GD} | | $V_d=V_{DRM} R_L=3.3K\Omega Tj=125^\circ\text{C}$ | I-II-III | 0.2 | - | - V |
| $dv/dt(2)$ | | $V_d=67\%V_{DRM}$ gate open; $Tj=125^\circ\text{C}$ | 40 | - | - | $\text{V}/\mu\text{s}$ |
| $(dv/dt)c(2)$ | | $(Dv/dt)c=0.1V/\mu\text{s } Tj=125^\circ\text{C}$ $(dv/d)tc=10V/\mu\text{s } Tj=125^\circ\text{C}$ | 8.5 3.0 | - | - | A/ms |

Dynamic Characteristics

| | | | | | | |
|-------------------------|---|----------------------|---|---|------------|---------|
| $V_T(2)$ | $I_{TM}=22.5A$ tp=380 μs | Tj=25°C | - | - | 1.55 | V |
| $V_{to}(2)$ $R_d(2)$ | Threshold voltage Dynamic resistance | Tj=125°C Tj=125°C | - | - | 0.85 25 | V mΩ |

Note 1: minimum I_{GT} is guaranteed at 5% of I_{GT} max.

Note 2: for both polarities of A2 referenced to A1.

Description

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

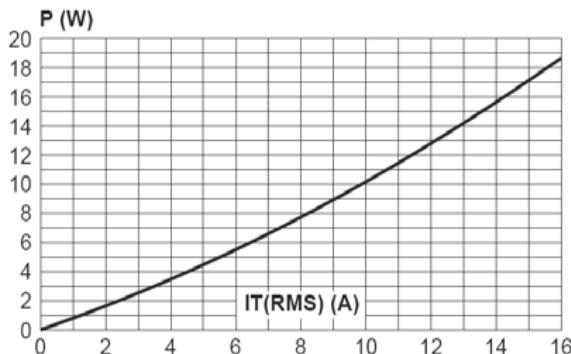


Fig. 2-1: RMS on-state current versus case temperature (full cycle).

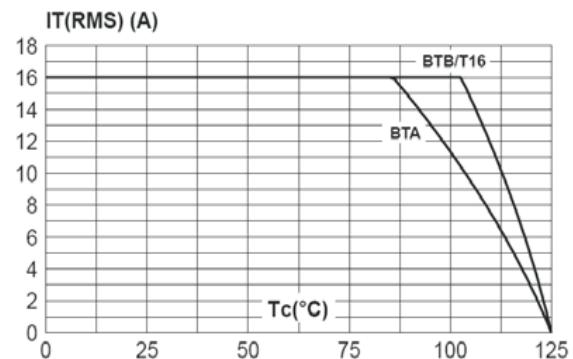


Fig. 2-2: D²PAK RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35 µm), full cycle.

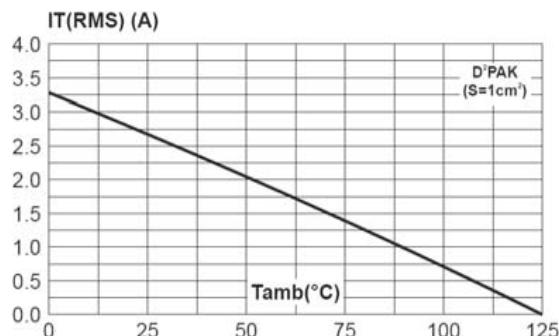


Fig. 3: Relative variation of thermal impedance versus pulse duration.

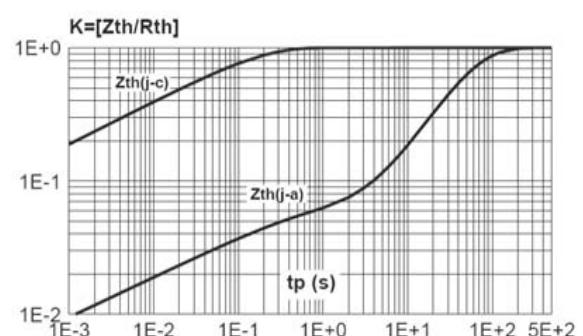


Fig. 4: On-state characteristics (maximum values)

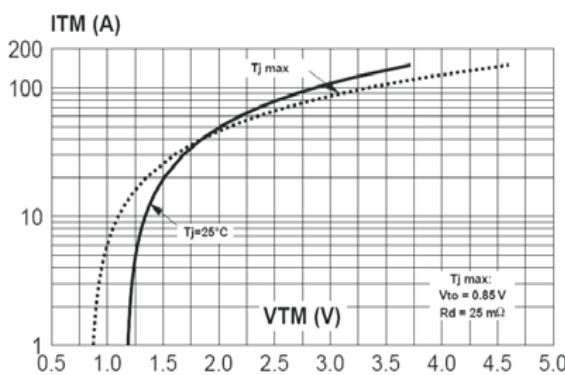
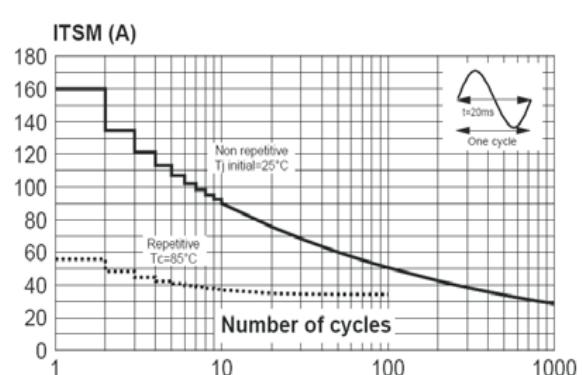


Fig. 5: Surge peak on-state current versus number of cycles.



Description

Fig. 6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of I^2t .

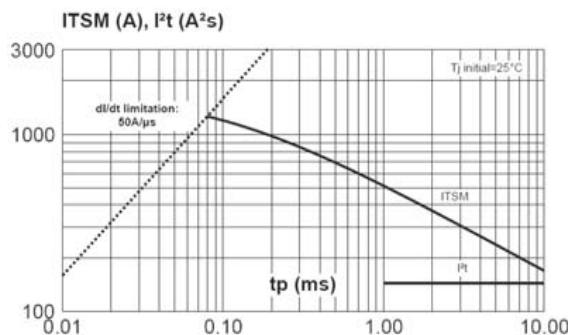


Fig. 7: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

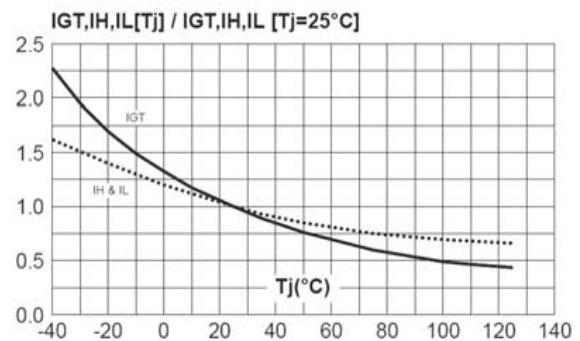


Fig. 8: Relative variation of critical rate of decrease of main current versus $(dV/dt)_c$ (typical values).

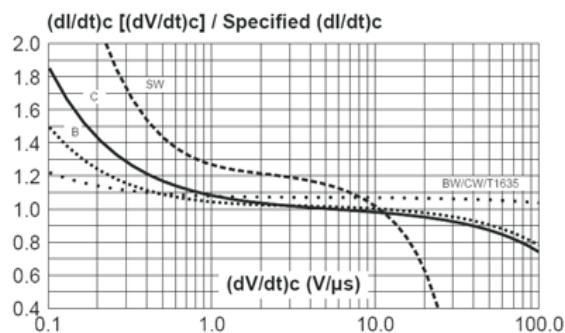


Fig. 9: Relative variation of critical rate of decrease of main current versus junction temperature.

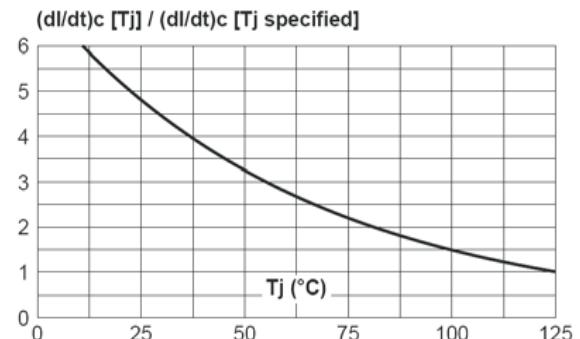
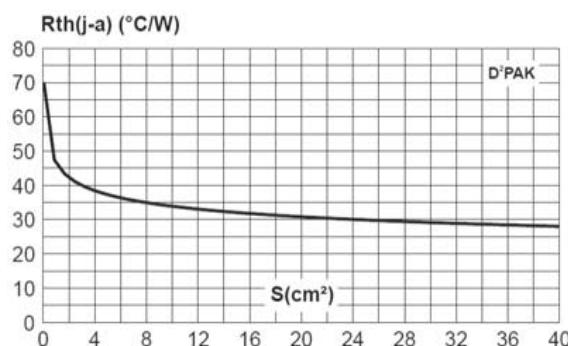
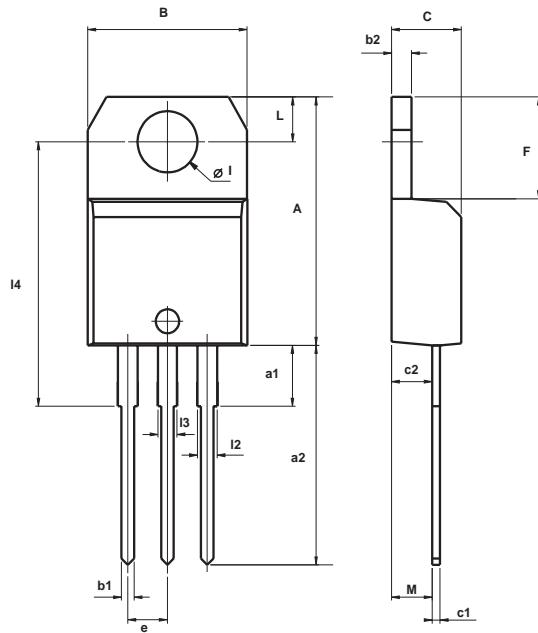


Fig. 10: D²PAK Thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: 35 μm).



Package Mechanical Data

TO-220AB (Plastic)



| REF. | DIMENSIONS | | | | | |
|------|-------------|-------|-------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 15.20 | | 15.90 | 0.598 | | 0.625 |
| a1 | | 3.75 | | | 0.147 | |
| a2 | 13.00 | | 14.00 | 0.511 | | 0.551 |
| B | 10.00 | | 10.40 | 0.393 | | 0.409 |
| b1 | 0.61 | | 0.88 | 0.024 | | 0.034 |
| b2 | 1.23 | | 1.32 | 0.048 | | 0.051 |
| C | 4.40 | | 4.60 | 0.173 | | 0.181 |
| c1 | 0.49 | | 0.70 | 0.019 | | 0.027 |
| c2 | 2.40 | | 2.72 | 0.094 | | 0.107 |
| e | 2.40 | | 2.70 | 0.094 | | 0.106 |
| F | 6.20 | | 6.60 | 0.244 | | 0.259 |
| I | 3.75 | | 3.85 | 0.147 | | 0.151 |
| I4 | 15.80 | 16.40 | 16.80 | 0.622 | 0.646 | 0.661 |
| L | 2.65 | | 2.95 | 0.104 | | 0.116 |
| I2 | 1.14 | | 1.70 | 0.044 | | 0.066 |
| I3 | 1.14 | | 1.70 | 0.044 | | 0.066 |
| M | | 2.60 | | | 0.102 | |